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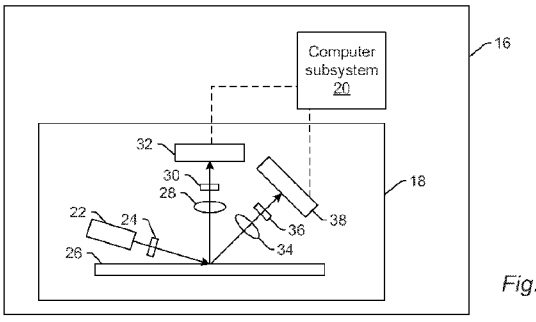


Fig. 2

(57) Abstract: Methods and systems for detecting defects on a wafer are provided.

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